

C0603C224K3RECTU

Aliases (C0603C224K3REC7867)

Specifications

Insulation Resistance

ESD SMD Comm X7R, Ceramic, 0.22 uF, 10%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0603, 0.5 mm



General Information		
Series	ESD SMD Comm X7R	
Style	SMD Chip	
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II	
Features	Temperature Stable, Class II	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	4.8 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

	Capacitance	0.22 uF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	10%
	Voltage DC	25 VDC
	ESD Level per AEC-Q200	25,000 V ESD Level
	Dielectric Withstanding Voltage	62.5 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	Dissipation Factor	3.5% 1 kHz 1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

2.2727 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

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